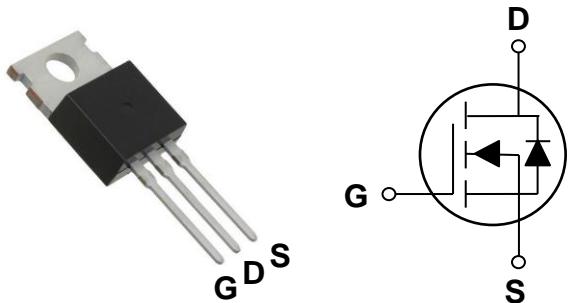


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO220 Pin Configuration



BVDSS	RDS(ON)	ID
65V	4.7mΩ	115A

### Features

- 65V, 115A, RDS(ON) = 4.7mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger



### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	65	V
V <sub>GС</sub>	Gate-Source Voltage	+20/-12	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	115	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	72	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	460	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	174	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	59	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	160	W
	Power Dissipation – Derate above 25°C	1.28	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.78	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	65	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.02	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =85°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =20V , V <sub>DS</sub> =0V	---	---	100	nA

**On Characteristics**

R <sub>DSON</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =15A	---	3.9	4.7	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A	---	6.2	8	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	1.5	2.5	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.1	---	mV/°C
gfs	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =3A	---	12	---	S

**Dynamic and switching Characteristics**

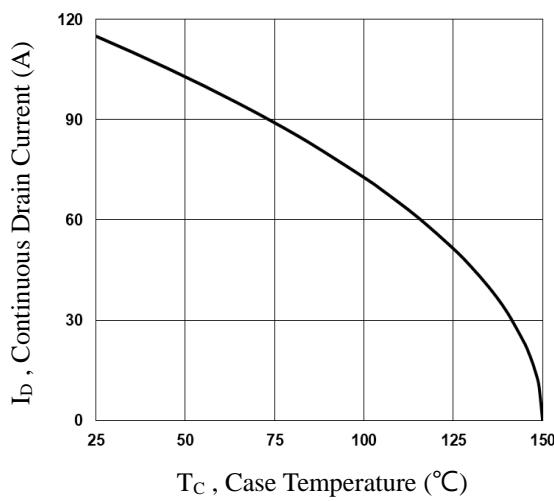
Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =48V , V <sub>GS</sub> =10V , I <sub>D</sub> =5A	---	54	108	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	5.2	10.4	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	16.1	32.2	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =6Ω I <sub>D</sub> =1A	---	10.6	21	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	16.5	33	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	48	96	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	78	150	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , F=1MHz	---	2940	5900	pF
C <sub>oss</sub>	Output Capacitance		---	850	1700	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	15	30	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	1.24	---	Ω

**Drain-Source Diode Characteristics and Maximum Ratings**

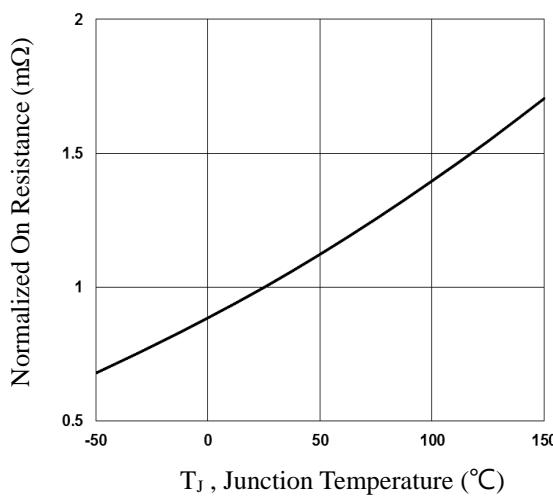
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	115	A
I <sub>SM</sub>	Pulsed Source Current		---	---	230	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	---	---	1	V

Note :

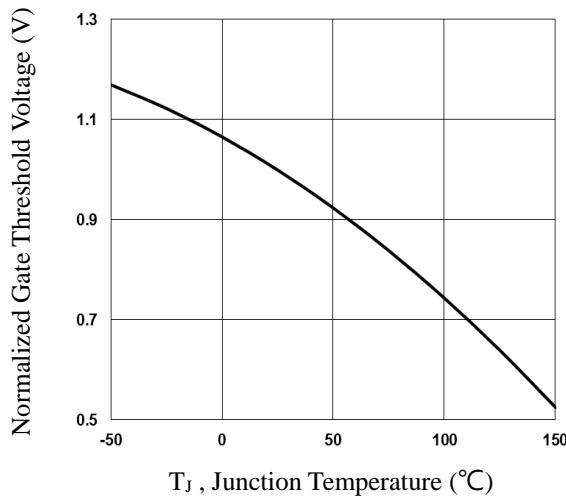
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=59A.,R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



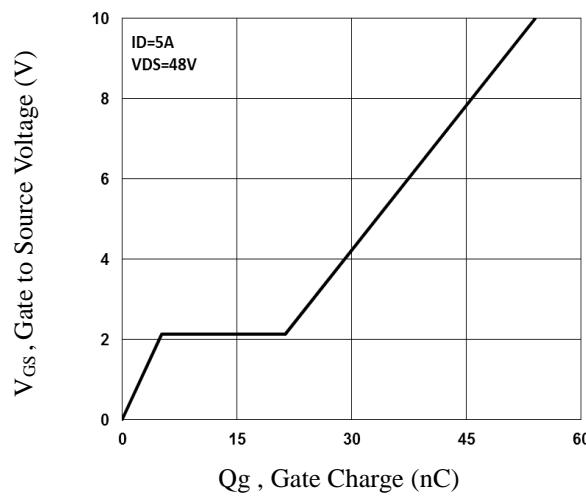
**Fig.1 Continuous Drain Current vs.  $T_C$**



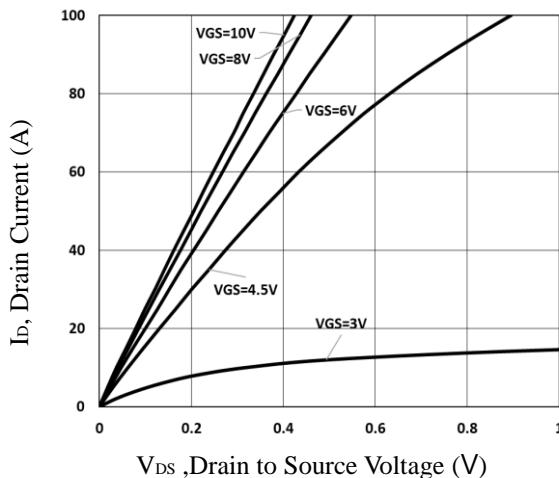
**Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$**



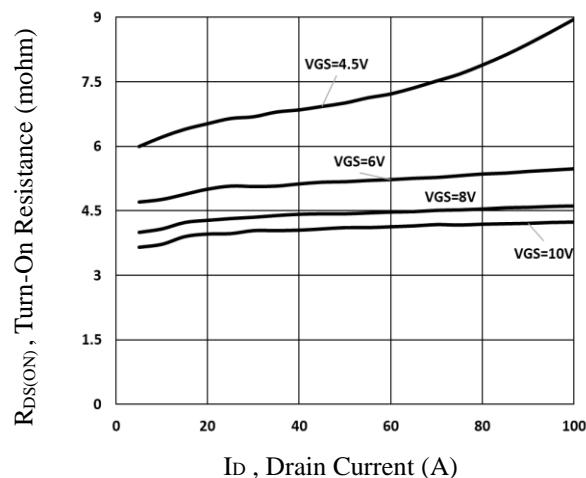
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



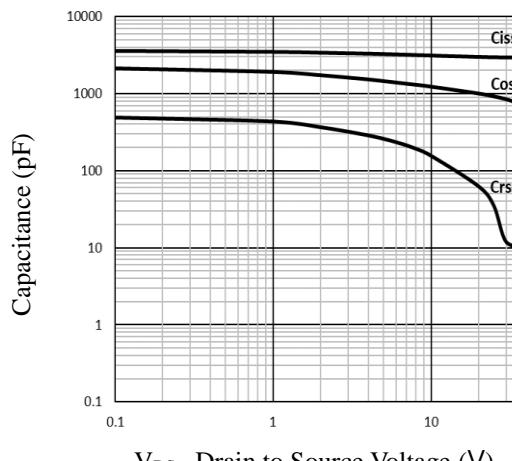
**Fig.4 Gate Charge Characteristics**



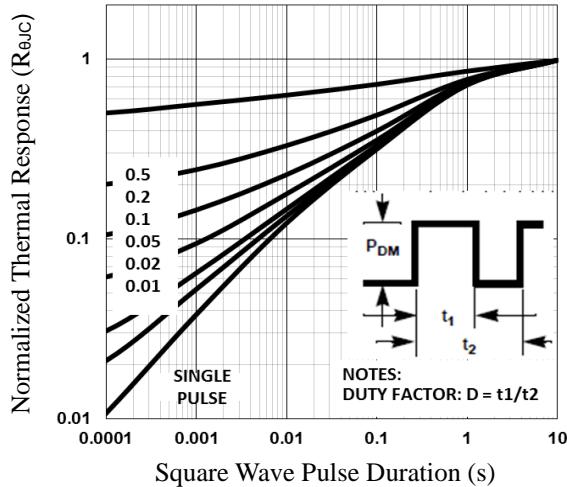
**Fig.5 Typical Output Characteristics**



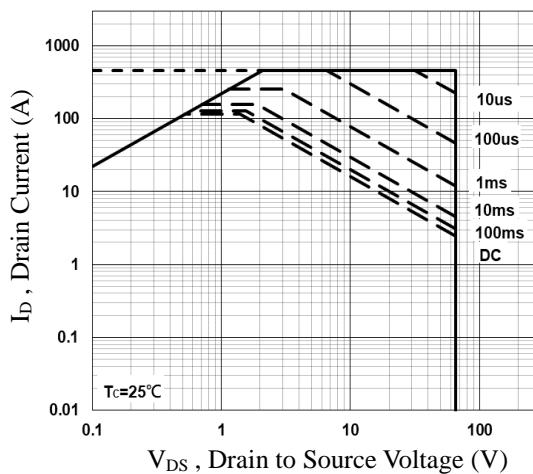
**Fig.6 Turn-On Resistance vs.  $I_D$**



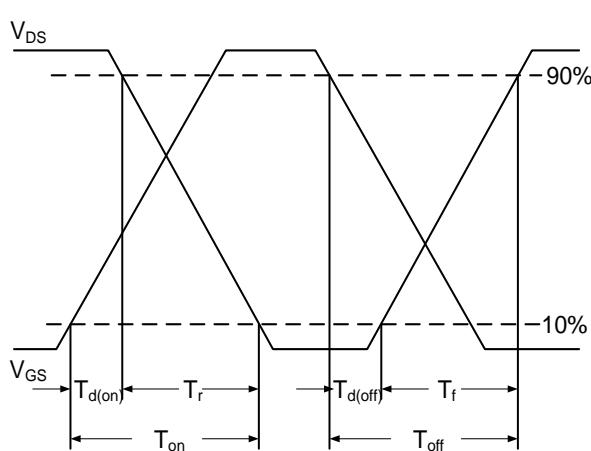
**Fig.7 Capacitance Characteristics**



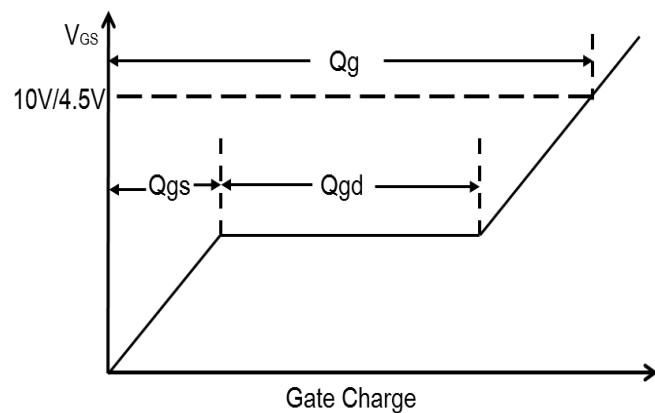
**Fig.8 Normalized Transient Impedance**



**Fig.9 Maximum Safe Operation Area**



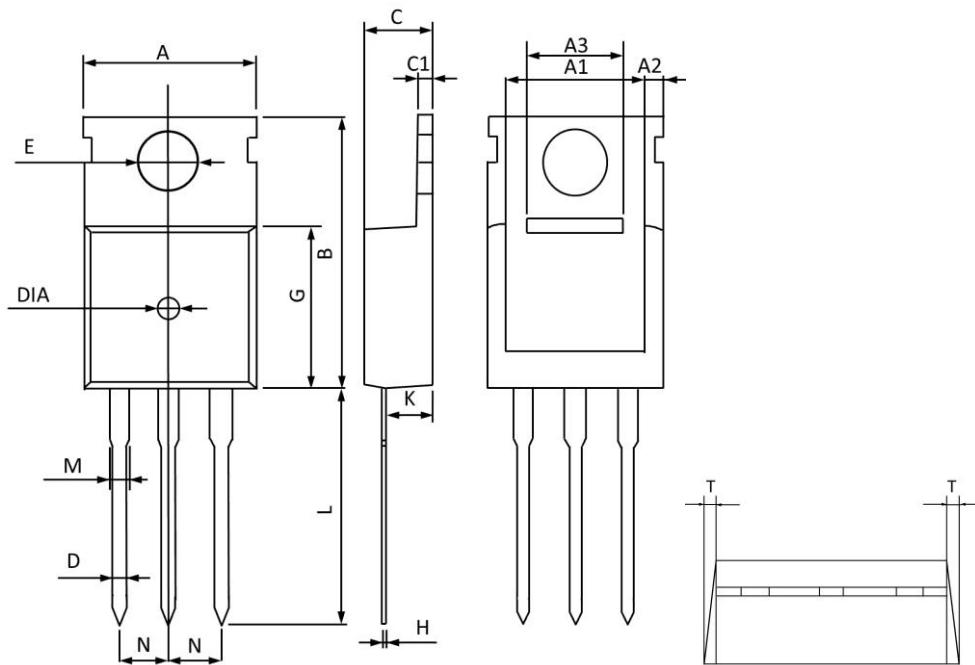
**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**



## TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.